



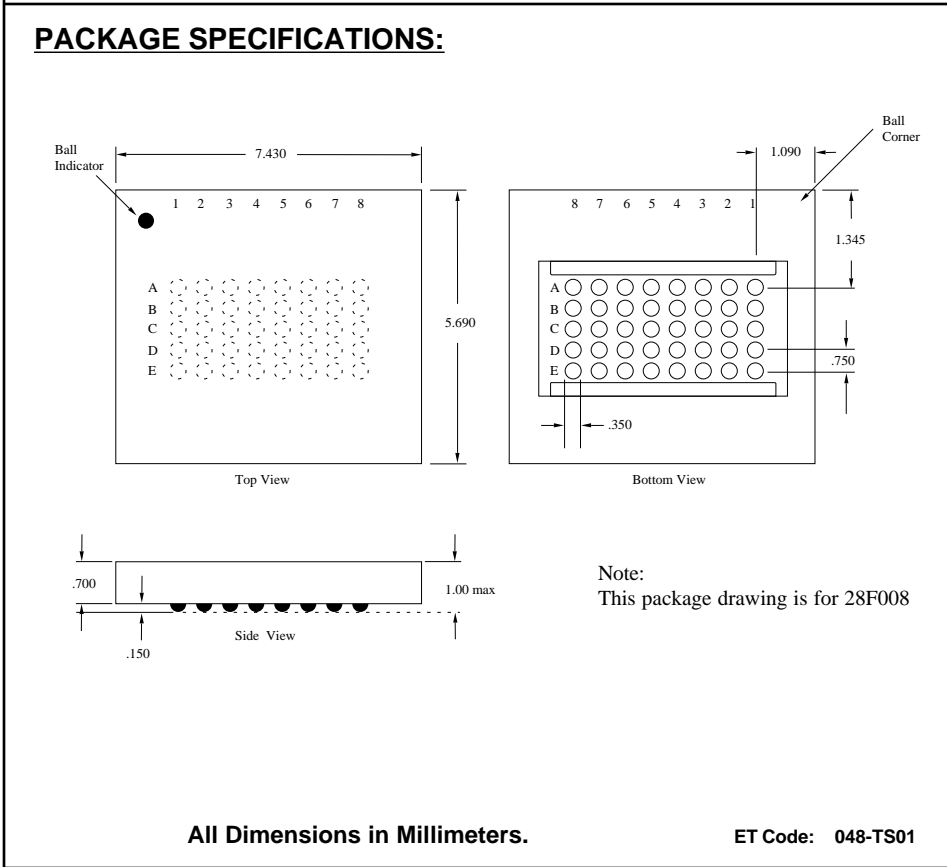
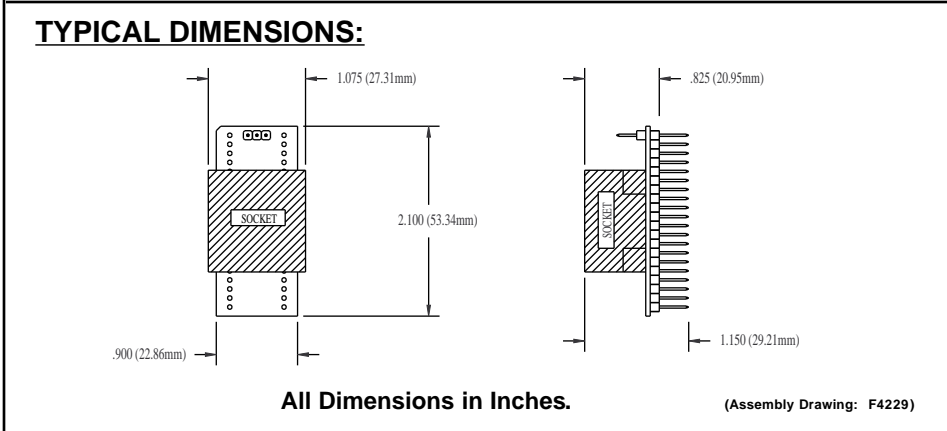
EMULATION TECHNOLOGY, INC.

Specification Number: M4229

# PROGRAMMING ADAPTER SPECIFICATION

Item: 404001BG0636YAM  
 Description: AS-40-40-01-4BG063-6YAM

**REPLACEMENT SOCKET:** S-BGA-00-040-A  
 Call Emulation Technology for a replacement socket price and delivery quote.



**CONNECTION TABLE:**

40-Ball $\mu$ BGA <sup>TM</sup> SOCKET	PIN Names	40-Pin DIP Base
A5	V <sub>PP</sub>	1
B5	CE#	2
A6	RP#	JMPR:3/1 <sup>3</sup>
C2	RY/BY#	4
-	-	5
C4	NC	6
C1	A20	7
C3	A19	8
B1	A18	9
A1	A17	10
D4(L2)	GND <sup>2</sup>	11(L2)
E2	DQ7	12
D2	DQ6	13
E3	DQ5	14
D3	DQ4	15
D5	DQ3	16
E6	DQ2	17
D6	DQ1	18
E7	DQ0	19
E1	OE#	20
D7	A0	21
E8	A1	22
D8	A2	23
C6	A3	24
C8	A4	25
C7	A5	26
B8	A6	27
A8	A7	28
C5	A8	29
E5(L5)	GND <sup>2</sup>	30(L5)
A7	A9	31
B7	A10	32
B6	A11	33
A3	A12	34
B4	A13	35
B3	A14	36
A2	A15	37
B2	A16	38
D1	WE#	39
A4/E4(L3&4)	V <sub>CC</sub> /V <sub>CCQ</sub> <sup>1</sup>	40(L3/4)

**Notes:**

- TSOP (V<sub>CC</sub>) and DIP40 (V<sub>CCQ</sub>) are tied to V<sub>CC</sub> layer 3. TSOP31 (V<sub>CCQ</sub>) and DIP40 (V<sub>CCQ</sub>) are tied to V<sub>CCQ</sub> layer 4.
- TSOP23 and 39 (GND) and DIP11 and 30 (GND) are tied to GND layers 2 and 5.

**Compatible Ball  $\mu$ BGA devices:** GU28F008S3 GU28F016S3  
 GU28F008S5 GU28F016S5  
 GU28F008SC GU28F016SC  
**Manufacturers:** Intel



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